

Glued SAM data sheet SAM- λ -A- τ -4.0-12.7g-c or SAM- λ -A- τ -4.0-12.7g-e

GaAs chip area standard: 4.0 mm x 4.0 mm
 optional: other dimensions on request

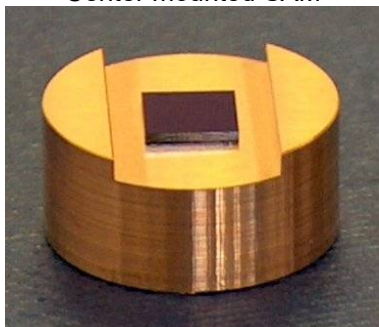
Chip thickness standard: 450 μ m

Front side protection the SAM is protected with a dielectric front layer.

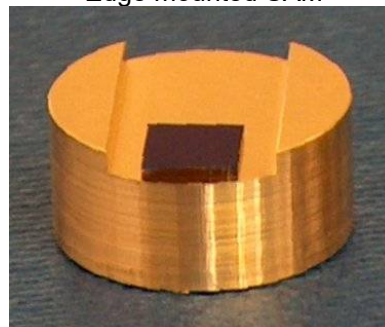
The SAM chip is glued on a gold plated Cu-cylinder with 12.7 mm \varnothing using a thermal conducting glue.
The glue provides a low thermal resistance between the SAM and the mount.

- The **standard** position of the SAM is at the center of the mount \rightarrow x = 4.0-12.7g-c.
- **Optional** the SAM can be soldered on the edge of the mount without extra charges
 \rightarrow x = 4.0-12.7g-e.

Center mounted SAM



Edge mounted SAM



Mount

Cu-cylinder, \varnothing = 12.7 mm
l = 6.0 mm